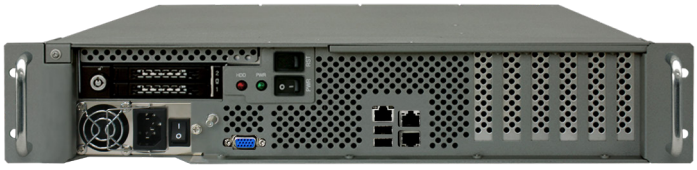
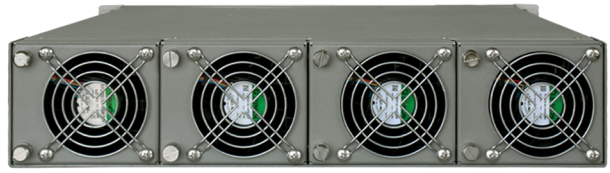
GAP-235PL - G6 Series
2U RUGGED SERVER

Intel® Xeon® Scalable Processors

Front I/O - Front Power Supply - Low Profile Boards





2U	355 mm	1-2	2TB	3	6
Platform	Depth	CPU	RAM	SSD	I/O Boards

GAP is a line of rugged servers and workstations with an aluminum construction, designed for applications that require robust and qualified MIL-GRADE equipment, suitable for operations in critical environments.

GAP-235PL G6 rugged servers feature single or dual socket Intel® Xeon® Scalable Processors (Skylake-SP / Cascade Lake-SP) supporting up to 28 cores and 56 thread, up to 38.5 MB cache, Intel® Ultra Path Interconnect, Intel® AVX-512, up to six memory channels and up to 48 PCIe 3.0 lanes. The integrated IPMI services support monitoring, control, and management functions sending alarm notifications in case of critical events.

GAP-235PL are designed for 19" rackmounting and have a 2U chassis with a depth of 355mm.
The front I/O and power supply input layout includes up to three removable SSDs and an optional slim DVD.
GAP-235PL rugged servers can host six low profile PCIe cards and feature rear removable fans.

GAP servers are designed to meet MIL-STD-810F for temperature and shocks, MIL-STD-167-1A for vibrations. Optionally, they can conform to MIL-STD-461 for EMI /EMC.
The I/O connectors and the power supply input can be provided with MIL-GRADE connectors upon request.

All units are delivered with their inventory list to ensure configuration control and reproducibility over time. Upon request, all server configurations can run specific thermal or mechanical environmental stress test.

FEATURES

- 2U Rugged Server - 355mm depth
- Single or Dual Processor
- Intel Xeon® Scalable Processors (I and II Gen)
- Front I/O connectors
- Front Power Input
- Removable fans
- AC or DC Power Supply
- Up to 3 SSD Hot Swap
- Up to 6 Low Profile PCIe boards
- Optional Conformal Coating
- MIL-STD-810G
- Optional MIL-STD-461

Technical Specifications

System

Processor	Intel® Xeon® Scalable Processors Family - Dual Socket P (LGA 3647) Intel® Xeon® Scalable Processors Family - Single Socket P (LGA 3647)
Memory	Up to 2TB ECC RDIMM, DDR4-2933MHz
Chipset	Intel® C621
Network	2 x RJ45 Gigabit Ethernet 1 x RJ45 dedicated IPMI
Storage	2.5" SATA Disk - RAID 0, 1, 5, 10
TPM	1 TPM Header
Motherboard I/O	Available at the rear: 1 x VGA, 2 x USB 2.0, 2 x GbE, 1 x IPMI LAN (Motherboard Dual Socket) 1 x VGA; 2 x USB 3.0, 2 x USB 2.0, 2 x GbE, 1 x IPMI LAN, 1 x COM (Motherboard Single Socket)
Expansion slots	Up to 6 PCIe Low Profile boards
Operative Systems	Windows® 8.1, Windows® 10 IoT Enterprise 2016, Windows® Server 2012 R2, Windows® Server 2016, Linux, Vmware
IPMI	IPMI2.0, SPM, Watchdog; SNMP and e-mail alarms and notifications
Monitoring	Monitoring, control, and management functions (fan speed, temperature, voltage, redundant power failure, power consumption, disk health, raid health, and memory health)

Power Supply

Power Supply	AC Single Power Supply DC Single Power Supply

Mechanical

Dimensions	483 x 88 x 355 mm
Construction	Aluminum with surface passivation treatment
Colour	Silver / RAL 9006
Mounting	2U 19" rackmount chassis Optional telescopic slides
Configuration	Front I/O and Power Supply
Front Panel	Led Power ON and SSD functionality; Power ON / OFF and System Reset
Drive Bay	1x slim 5.25" ; 1x 3.5" bay

Environmental - (Design to meet)

Operating Temperatures	0°C to +50°C MIL-STD-810H, Method 501.7 & 502.7 -20°C to +60°C (depending on configuration)
Storage Temperature	-40°C to +70°C MIL-STD-810H, Method 501.7 & 502.7
Humidity	5% – 95% non-condensing MIL-STD-810H 507.6
Operating Vibrations	MIL-STD-167-1A, Type I
Not Operating Vibrations	1.17 Grms, 5-500 Hz MIL-STD-810H, Method 514.8
Operating Shocks	20g / 11ms – half sine MIL-STD-810G, Method 516.7
EMC	Directive 2014/35/UE-LVD | Directive 2014/30/UE-EMC | Directive 2011/65/UE - RoHS Regulation EC No 1907/2006 | MIL-STD-461G (on request)

GAP servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.